

Special Issue

AI and IoT in Manufacturing

Message from the Guest Editor

Modern technologies with artificial intelligence are widely used in the processing industry and serve, among other things, to boost efficiency and automatization of production processes, which in turn allows for increased productivity of companies while at the same increasing their competitiveness. The objective of this Special Issue is to present the latest advances and developments including new systems, tools, methods, and techniques to dedicated the application of manufacturing. In this Special Issue we welcome both original research papers and review articles on diverse topics such as:

- Artificial Intelligence (AI)
- Intelligent manufacturing
- Big data
- Industry 4.0
- Internet of Things
- Manufacturing systems
- Cloud manufacturing
- Manufacturing processes
- Artificial vision
- Management in new digitally powered manufacturing concepts

Guest Editor

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closed (31 March 2021)



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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